

SIDE ENTRY, TOP ENTRY AND BOTTOM ENTRY MODULAR JACKS

1. INTRODUCTION.

This specification covers the requirements for the application of the following styles of AMP* Modular Jacks for printed circuit board applications:

- Side Entry, low profile, single and multi-port
- Top Entry
- Bottom Entry

2. REFERENCE MATERIAL.

2.1 Customer Drawing.

A customer drawing is available for each partnumber assigned to this product line. In the event of conflict between this specification and the customer drawing, the customer drawing will take precedence.

2.2 Product Specification.

Product Specification 108-19064 provides information pertaining to performance, testing and quality requirements.

3. REQUIREMENTS.

3.1 Printed Circuit Board Lay-out.

The dimensions for the printed circuit board lay-out are given on the customer drawing of that Modular Jack. Also the dimensions for the mounting hole in the printed circuit board for Bottom Entry Modular Jacks are shown on the customer drawing for that particular partnumber.

3.2 Panel cut-out Guidelines.

The panel stops of Top Entry Modular Jacks should lean against the innerside of the panel. This to prevent that pull forces, coming from the Modular Plug lead, loose the contacts from the Modular Jack or that stresses are exerted upon the solder joints.

DR. M. van ESSEN

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3.3 Alignment.

Side Entry and Top Entry Modular Jacks shall be placed flush with the surface of the printed circuit board. See Figure 2a.

Bottom Entry Modular Jacks have latches which secure the Jack to the printed circuit board. Touch these latches by your fingers during insertion in the hole in the printed circuit board. this is to aid the inward movement of the latches. The often seen very sharp edges on the hole in the printed circuit board do have a cutting effect on the latches and "hamper" the inward movement of them. The Bottom Entry Modular Jacks can for this reason not be installed by an automatic pick-and-place machine.

4. SOLDERING AND CLEANING.

Contacts shall be fluxed prior to soldering using a medium active rosin or a medium active organic flux.

Proper flux selection depends on the type of printed circuit board and any components already mounted. Flux must also be compatible with user's flow solder line and with manufacturing and safety requirements.

The cleaning procedure selected will depend on the type of flux and the degree of cleanliness required by the user.

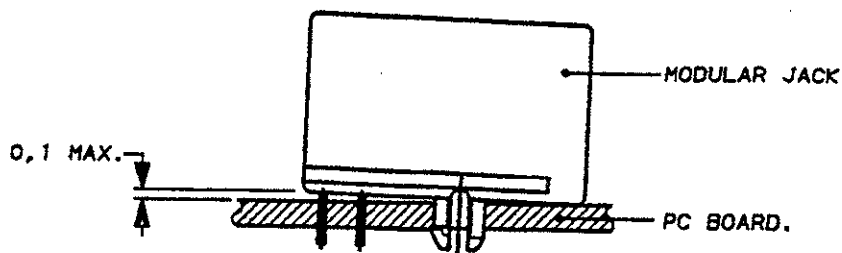


Figure 2a